CALL FOR PAPERS

The 27th edition of the IEEE International Interconnect Technology Conference (IITC) will be held June 3-6, 2024 in San Jose, California. Authors are encouraged to submit their original work describing innovative research and development in the critically important field of on-chip interconnects. The conference seeks papers on all aspects of BEOL/MOL interconnects and metallization, including design, unit process, integration and reliability. **The deadline for submission of abstracts is February 12, 2024**.

IEEE IITC is sponsored by the IEEE Electron Devices Society as the premier conference for interconnect technology devoted to leading-edge research in the field of advanced metallization and 3D integration for ULSI IC applications. The conference seeks papers on all aspects of BEOL/MOL interconnects and metallization, including design, unit process, integration and reliability.

Applications of Interest

- Advanced interconnects: low-k interconnects, optical, wireless, and carbon-based interconnects, Airgap, 1D/2D interconnects, beyond Cu…
- Emerging BEOL Integration flows such as semi-damascene
- 3D integration & packaging concerns: Wafer-to-Wafer/Chip-to-Wafer bonding, RDL's and Interposers, Through Si Via, Non-destructive, high throughput methods to identify defects, backside power distribution network (BSPDN), thermal management
- Contacts on MOS devices: Silicide, III-V, 2D materials…
- Memory architecture: CBRAM, PCRAM, ReRAM, MRAM, FeRAM, DRAM, 3DNAND…
- Novel System and Emerging Technology: Energy harvesting, brain-inspired computing…
- Novel Form Factors: flexible electronics, wearables…

Topics of Interest

- Process integration, advanced patterning for MOL/BEOL
- Materials and Unit Processes (Dielectrics, metals, barriers, Wet, CMP, PVD, CVD, ALD, selective deposition/SAMs, patterning, advanced cleaning and surface treatment)
- Reliability and Failure analysis, characterization, techniques, and methods
- Advanced material/process characterization, system-technology & design-technology co-optimization, and modelling techniques

Abstract Information
Abstracts must be no more than 3 pages in length. Details of abstract submission, including a template may be found at **www.iitc-conference.org**. Submissions will be reviewed for acceptance as an oral presentation or poster. Accepted abstracts will be published digitally by IEEE as IITC Conference Proceedings without further changes.